

# VIGON® A 201

## Water-based defluxing agent for spray-in-air cleaning processes



VIGON® A 201 provides excellent cleaning performance in spray-in-air cleaning processes for the cleaning of capillary spaces, e.g. under low standoff components. Being used at low concentration the MPC® based cleaning agent VIGON® A 201 is especially suitable for removing flux residues from leaded as well as lead-free NoClean solder pastes. Its excellent compatibility with sensitive metal alloys leads to shiny solder joints after cleaning without the need for any additives.

| Areas of application:<br>PCB cleaning |    | Further information for this product:  |
|---------------------------------------|----|--|
| Low solid flux residues               | ++ | <b>Technical Information Sheet 2:</b><br>Overview of all fluxes and solder pastes tested<br><br><b>Technical Information Sheet 3:</b><br>Overview regarding material compatibility<br><br><b>MPC® Technology Sheet:</b><br>Additional information on MPC® Technology |
| Rosin based flux residues             | ++ |  |
| Water soluble flux residues           | ++ |  |
| Solder paste (unsoldered)             | +  |  |
| SMT or conductive adhesives           | o  |  |

++ highly recommended, best results      + recommended      o possible

### Free-of-Charge Cleaning Trials & Surface Analytics at ZESTRON's Technical Centers



Free-of-charge cleaning trials can be performed at one of ZESTRON's Global Technical Centers. ZESTRON's European, North American and Asian Technical Centers feature spray-in-air, ultrasonic or spray-under-immersion processes. This provides an extensive overview on all available processes by leading international equipment manufacturers.



Upon completion of the cleaning trials, extensive analytical tests such as SIR and ionic residue measurements can be performed.

Please consult with ZESTRON's Application Technology Centers regarding future cleaning trials: Phone +49-841-635-26; Email: techsupport@zestron.com

### Advantages compared to other cleaners:

- Successfully cleans under low standoff components such as Micro BGAs, Flip Chips, and 01005 components.
- Specifically effective for lead-free NoClean solder pastes.
- Even at low concentration and cleaning temperatures, VIGON® A 201 provides excellent cleaning results.
- Furnishes shiny solder joints on assemblies after cleaning without any additional additive necessary.
- High bath loading capacity ensures extended bath life, low maintenance costs and reduced costs per cleaned part.
- VIGON® A 201 is easy rinsable and does not leave any residues on the surfaces.
- Does not foam, even in high pressure applications.

Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.

| Process                         | Cleaning     | Rinsing  | Drying                     |
|---------------------------------|--------------|----------|----------------------------|
| Spray-in-air (Inline and Batch) | VIGON® A 201 | DI-water | Hot air or circulating air |
| Centrifugal Cleaning            | VIGON® A 201 | DI-water | Hot air or circulating air |

| Technical Data  |                                  |                     |
|---|----------------------------------|---------------------|
| Please note that the information below represents VIGON® A 201 at 15 % concentration. |                                  |                     |
| Density   | (g/ccm) at 20°C/68°F             | 1                   |
| Surface tension   | (mN/m) at 25°C/77°F              | 28.7                |
| Boiling range   | °C/°F                            | > 100 / 212         |
| Flash point   | °C/°F                            | None                |
| pH-Value  | 10g/l H <sub>2</sub> O           | 10.51               |
| Vapor pressure  | (mbar) at 20°C/68°F              | 20                  |
| Cleaning temperature  | °C/°F                            | 40 – 60 / 104 - 140 |
| Solubility in water   |                                  | Soluble             |
| Application concentration <sup>1</sup>  | %                                | 15 - 20             |
| HMIS Rating   | Health- Flammability- Reactivity | 1 - 0 - 0           |

<sup>1</sup> VIGON® A 201 is recommended to be diluted with DI-water only.

## LEAD-FREE COMPLIANT



VIGON® A 201 meets the RoHS & WEEE guidelines, current worker safety standards as well as the actual applicable environmental requirements. ZESTRON voluntary avoids the use of critical substances during product development.



Extensive tests confirmed the qualification of VIGON® A 201 for the cleaning of lead-free solder pastes. For detailed results, please request our Technical Information Sheet 2.

## Filter recommendation:

To take full advantage of the MPC® Technology and further expand VIGON® A 201 bath life, filtration is recommended. For details, please request our "Filter Recommendation" sheet.

## Environmental, health and safety regulations:

VIGON® A 201 is water-based and biodegradable. The cleaning agent is formulated free of any halogenated compounds. Refer to the MSDS for specific handling precautions and instructions.

## Availability/Storage:

VIGON® A 201 is available as concentrate in 1L bottles, 5L or 25L canisters and 200L drums. Store VIGON® A 201 in the original container at a temperature between 5-30°C / 41-86°F. The product has a minimum shelf life of 5 years in factory sealed containers.

## Cleaning Standards:

Electronic assemblies cleaned with VIGON® A 201 in a ZESTRON specified process meet the following industry standards:

- IPC-A-610 Visual cleanliness
- J-STD 001D Ionic cleanliness
- IPC-TM 650 and DIN 32513 (surface resistance)
- J-STD 003 solderability